

Tech-X Corporation



**Visit Tech-X at Booth #101 at the AVS 58th International Symposium & Exhibition,
October 31 - November 4, at the Nashville Convention Center**

Tech-X Corporation invites you to visit our booth (Booth #101) at the AVS 58th International Symposium & Exhibition (<http://www2.avs.org/symposium/AVS58/pages/greetings.html>), October 31 – November 4, at the Nashville Convention Center.

We are proud to present the latest release of our electromagnetic plasma simulation software, VORPAL (<http://vorpal.txcorp.com>). VORPAL 5.0.0 includes an improved visualization environment based on VisIt, the capability to perform simulations in cylindrical coordinates, an improved framework for particle collisions, the ability to execute electromagnetic simulations on GPUs, and improved restart performance. Please stop by for a demonstration or to receive an evaluation copy of this new release.

Personnel from Tech-X will be presenting at the following time:

**Plasma Science and Technology Division
Session PS-FrM
Friday, November 4 8:20-12:00, Room 201**

8:40 Kinetic Effects in Low Pressure Capacitively Coupled Plasmas, A. Likhanskii, P. Stoltz, Tech-X Corporation, Boulder, CO

###

© 2011 Tech-X Corporation

5621 Arapahoe Ave, Suite A • Boulder, CO 80303
(303) 448-0727 • FAX: (303) 448-7756
www.txcorp.com